

PATENT
TESSERA 3.3-018

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

45 JUL 30 1993
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In re Patent Application of :
Khandros et al.
Serial No. 08/030,194 : Group Art Unit:
Filed: April 28, 1993 : Examiner:
For: SEMICONDUCTOR CHIP : Date: July 27, 1993
ASSEMBLIES, METHODS OF :
MAKING SAME AND COMPONENTS:
FOR SAME

X
Hon. Commissioner of Patents
and Trademarks
Washington, D.C. 20231

CERTIFICATION PURSUANT TO 37 C.F.R. { 1.97(e)(1)}

Sir:

Pursuant to 37 C.F.R. { 1.97(e)(1), undersigned counsel hereby certifies that each item of information contained in the accompanying Information Disclosure Statement was cited in a counterpart foreign patent office application to the above-referenced patent application not more than three months prior to the filing of said statement.

Respectfully submitted,

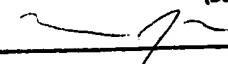
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